

Features

1) Low on-resistance

4) Parallel use is easy

3) Drive circuits can be simple

5) Pb-free plating ; RoHS compliant

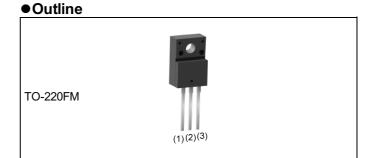
2) Fast switching

Application

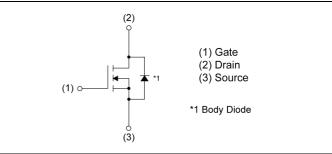
Switching

R6009ENX

V _{DSS}	600V
R _{DS(on)} (Max.)	0.535Ω
Ι _D	±9A
P _D	48W



Inner circuit



Packaging specifications

Code	Packing
C7 G	Tube
C7	Tube*
- (Blank)	Bulk*

*Package dimensions are different

• Absolute maximum ratings ($T_a = 25^{\circ}C$,unless otherwise specified)

	a	• •		
Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	600	V
Continuous drain current		۱ _D *1	±9	А
Pulsed drain current		I _{DP} *2	±18	А
Gate - Source voltage	static	V	±20	V
	AC(f>1Hz)	V_{GSS}	±30	V
Avalanche current, repetitive		I _{AS}	1.4	А
Avalanche energy, single pulse		E_{AS}^{*3}	153	mJ
Avalanche energy, repetitive		E_{AS}^{*3}	0.23	mJ
Power dissipation $(T_c = 25^{\circ}C)$		P _D	48	W
Junction temperature	Tj	150	°C	
Operating junction and storage te	emperature range	T _{stg}	-55 to +150	°C

● Absolute maximum ratings (T_a = 25°C)

Parameter	Symbol	Conditions	Values	Unit
Reverse diode dv/dt	dv/dt	-	15	V/ns
Drain - Source voltage slope	dv/dt	V _{DS} = 480V, T _j = 25°C	50	V/ns

•Thermal resistance

Deremeter	Symbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}^{*4}	-	-	2.6	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	70	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics (T_a = 25°C)

Deremeter	Sumbol	Conditions		Linit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	600	-	-	V
		V _{DS} = 600V, V _{GS} = 0V				
Zero gate voltage drain current	I _{DSS}	T _j = 25°C	-	0.1	100	μA
		T _j = 125°C	-	-	1000	
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	-	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = 10V, I _D = 1mA	2	-	4	V
		V _{GS} = 10V, I _D = 2.8A				
Static drain - source on - state resistance	${\sf R}_{\sf DS(on)}^{*5}$	T _j = 25°C	-	0.500	0.535	Ω
		T _j = 125°C	-	1.00	-	
Gate resistance	R _G	f =1MHz, open drain	-	9.6	-	Ω



•Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sumphal	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Transfer Admittance	Y _{fs} * ⁵	V _{DS} = 10V, I _D = 4.5A	2.3	4.5	-	S
Input capacitance	C _{iss}	V _{GS} = 0V	-	430	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	470	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	55	-	
Effective output capacitance, energy related	C _{o(er)}	V _{GS} = 0V	-	23	-	- 5
Effective output capacitance, time related	C _{o(tr)}	$V_{DS} = 0V$ to 480V	-	100	-	pF
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 300 \text{V}, \text{V}_{GS} = 10 \text{V}$	-	25	-	
Rise time	t _r *5	I _D = 4.5A	-	35	-	
Turn - off delay time	t _{d(off)} *5	R _L ≃ 66.7Ω	-	75	-	ns
Fall time	t _f *5	R _G = 10Ω	-	30	-	

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Parameter	Symbol Conditions	Conditions		Linit		
		Min.	Тур.	Max.	Unit	
Total gate charge	Q_g^{*5}	V _{DD} ≃ 300V,	-	23	-	
Gate - Source charge	Q_{gs}^{*5}	I _D = 9.0A,	-	4	-	nC
Gate - Drain charge	Q_{gd}^{*5}	V _{GS} = 10V	-	15	-	
Gate plateau voltage	V _(plateau)	V _{DD} = 300V, I _D = 9A	-	6.4	-	V

*1 Limited only by maximum channel temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L \doteqdot 100mH, V_{DD}=50V, R_G=25 Ω , STARTING T_j=25°C

*4 T_C=25°C



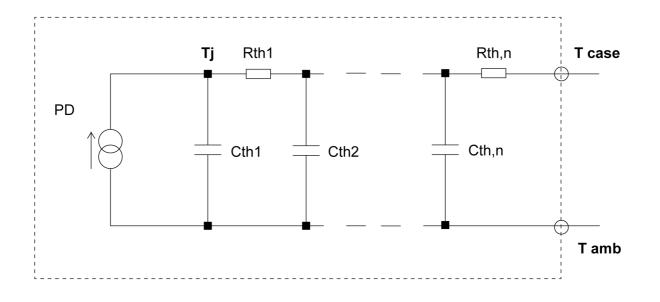
^{*5} Pulsed

•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Deremeter	Sumbol	Conditions	Values			- Unit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Continuous forward current	۱ _S *1	T - 25°0	-	-	9	А	
Pulse forward current	ا _{SP} *2	T _C = 25°C	-	-	18	А	
Forward voltage	V_{SD}^{*5}	V _{GS} = 0V, I _S = 9.0A	-	-	1.5	V	
Reverse recovery time	t _{rr} *5		-	380	-	ns	
Reverse recovery charge	Q _{rr} *5	I _S = 9A di/dt = 100A/µs	-	3.8	-	μC	
Peak reverse recovery current	۲ _{rrm} *5		-	20	-	А	

• Typical transient thermal characteristics

Symbol	Value	Unit	-	Symbol	Value	Unit
R _{th1}	0.344		-	C_{th1}	0.00137	
R _{th2}	1.15	K/W	_	C_{th2}	0.0145	Ws/K
R _{th3}	2.2		-	C _{th3}	0.451	





• Electrical characteristic curves

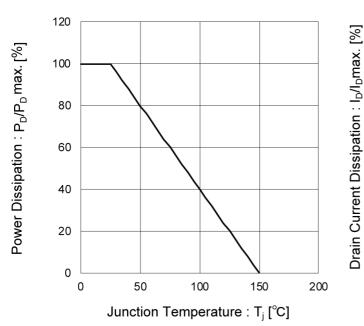


Fig.1 Power Dissipation Derating Curve

Fig.2 Drain Current Derating CurveArea

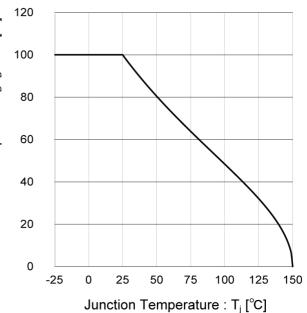
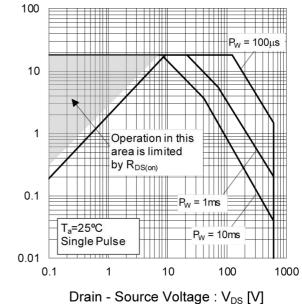


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

1000 Normalized Transient Thermal Resistance : r(t) 100 T_a = 25℃ Single Pulse 100 $R_{th(j-a)(t)} = r_{(t)} \times R_{th(j-a)}$ R_{th(j-a)} = 70°C/W 10 Drain Current : I_D [A] 10 1 1 0.1 by R_{DS(on)} D = 1 top 0.01 D = 0.5 0.1 D = 0.1 D = 0.050.001 D = 0.01 T_a=25℃ D = Single Single Pulse 0.0001 0.01 0.0001 0.001 0.01 0.1 100 1000 0.1 1 10 1 Pulse Width : Pw [s]

Fig.4 Maximum Safe Operating Area





• Electrical characteristic curves

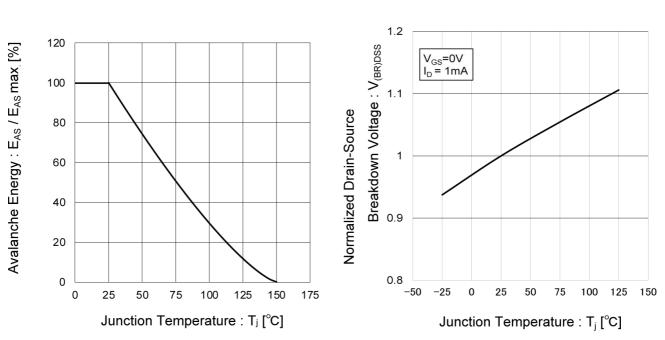


Fig.5 Avalanche Energy Drating Curve vs. Junction Tempreture

Fig.7 Typical Output Characteristics(I)

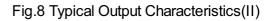
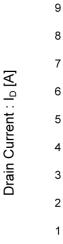
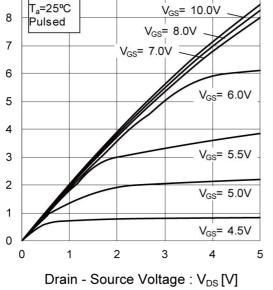
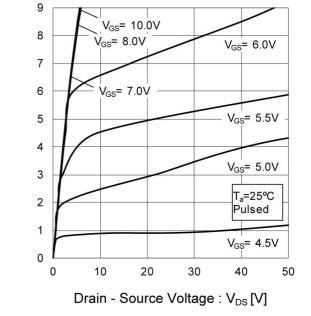


Fig.6 Normalized Breakdown Voltage vs.

Junction Temperature







Drain Current : I_D [A]



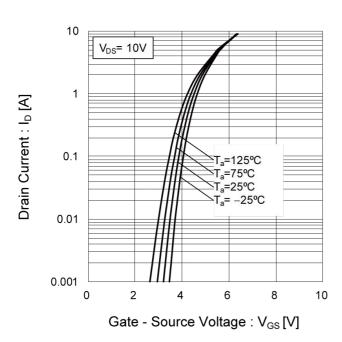
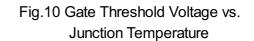


Fig.9 Typical Transfer Characteristics



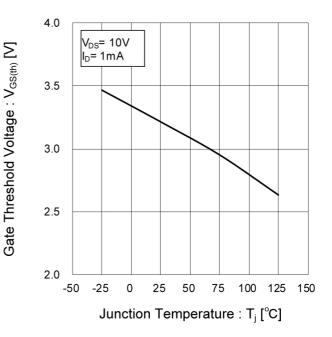
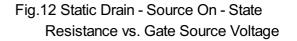
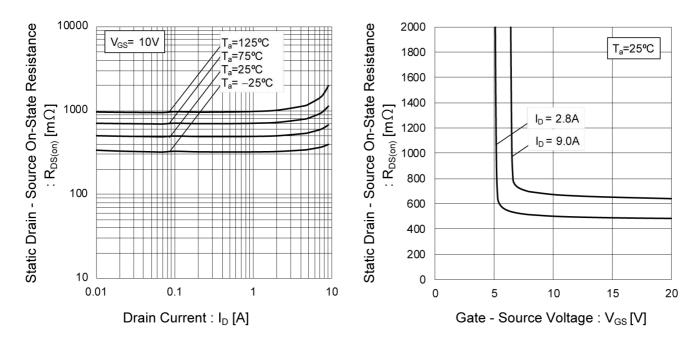


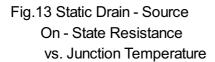
Fig.11 Static Drain - Source On - State Resistance vs. Drain Current







•Electrical characteristic curves



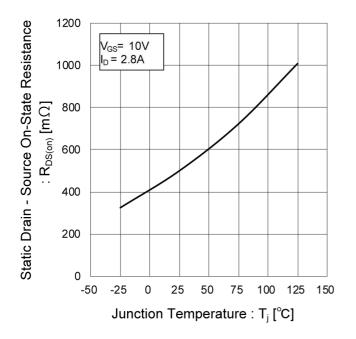


Fig.14 Typical Capacitance vs. Drain - Source Voltage

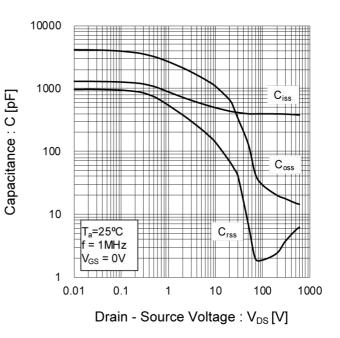


Fig.15 Switching Characteristics

Fig.16 Typical Gate Charge

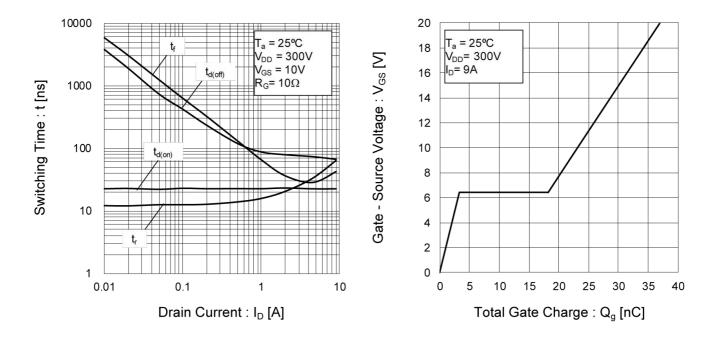




Fig.18 Reverse Recovery Time vs. Source Current

• Electrical characteristic curves

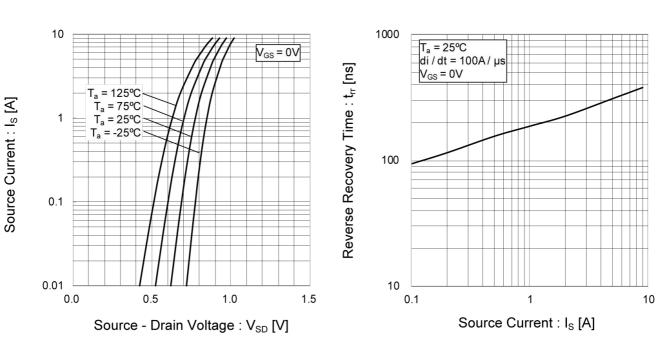


Fig.17 Source Current vs. Source - Drain Voltage





Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

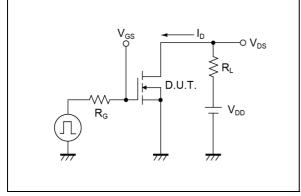


Fig.2-1 Gate Charge Measurement Circuit

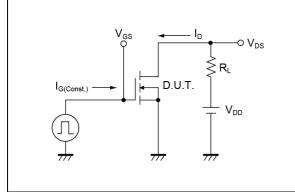


Fig.3-1 Avalanche Measurement Circuit

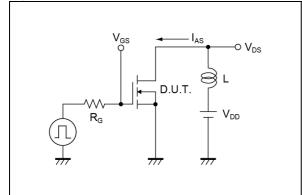


Fig.4-1 trr Measurement Circuit

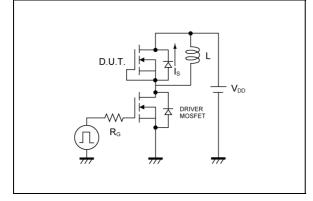


Fig.1-2 Switching Waveforms

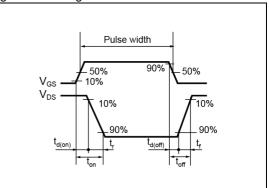


Fig.2-2 Gate Charge Waveform

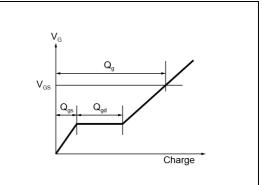


Fig.3-2 Avalanche Waveform

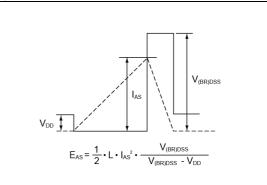
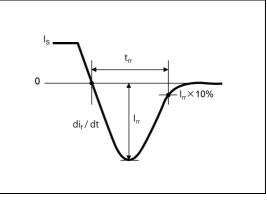
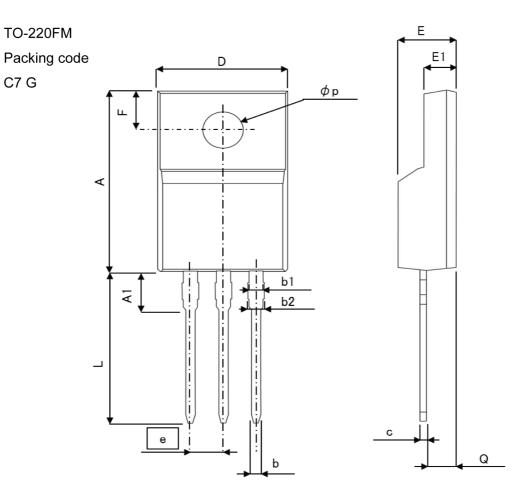


Fig.4-2 trr Waveform





Dimensions

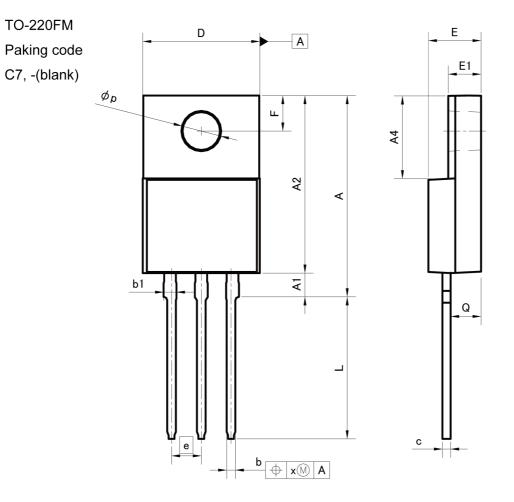


	DIM		INC	HES
DIM	MIN	MAX	MIN	MAX
A	15.67	16.27	0.617	0.641
A1	3.03	3.43	0.119	0.135
b	0.70	0.95	0.028	0.037
b1	1.00	1.40	0.039	0.055
b2	1.10	1.50	0.043	0.059
с	0.45	0.65	0.018	0.026
D	9.90	10.30	0.390	0.406
E	4.60	5.00	0.181	0.197
E1	2.44	2.74	0.096	0.108
е	2.	54	0.1	00
F	3.10	3.50	0.122	0.138
L	12.6	13.6	0.946	0.535
р	2.98	3.38	0.117	0.133
Q	2.25	3.25	0.089	0.128

Dimension in mm/inches



Dimensions



	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.90	0.028	0.035
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.390	0.406
E	4.40	4.80	0.173	0.189
е	2.	54	0.1	00
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.110	0.126
Ĺ	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
x	_	0.38	_	0.015

Dimension in mm/inches



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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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